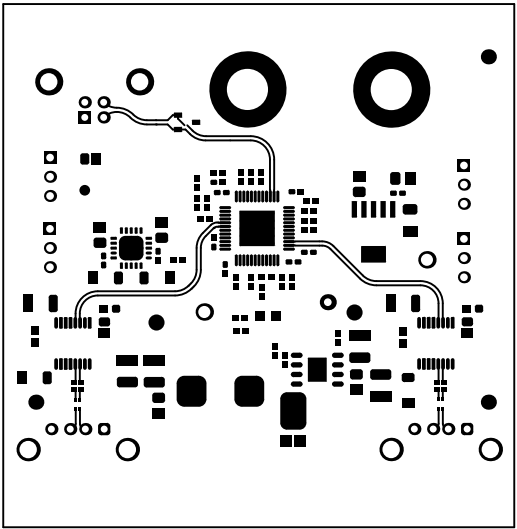
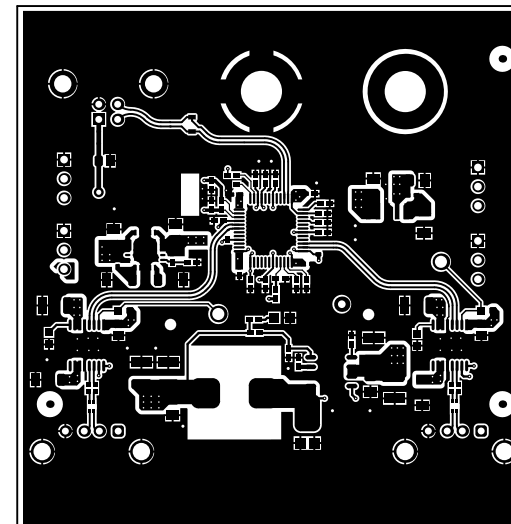


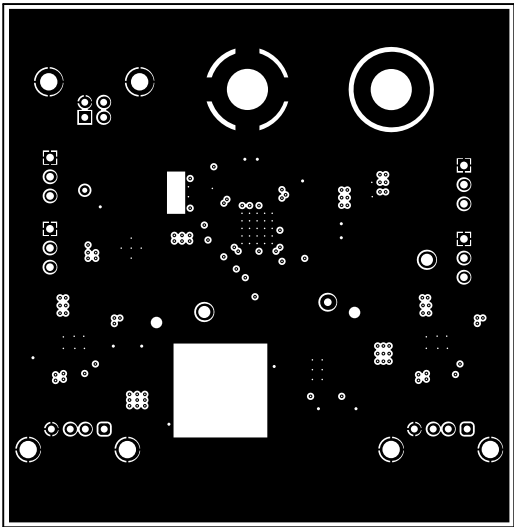
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00887	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 00887		
PLOT NAME = Top Overlay	GENERATED : 7/18/2016 1:36:26 PM	TEXAS INSTRUMENTS	



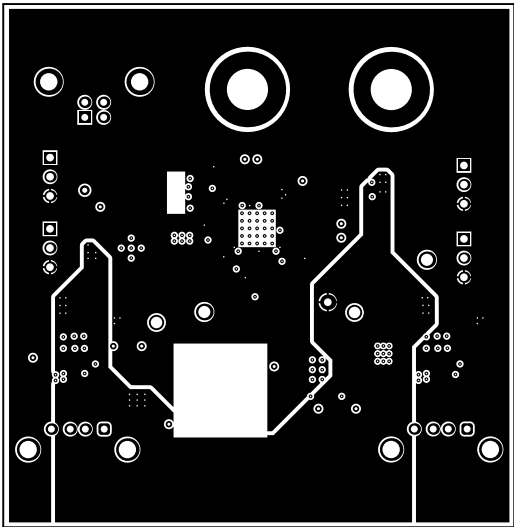
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00887	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 00887		
PLOT NAME = Top Solder Mask	GENERATED : 7/18/2016 1:36:26 PM	TEXAS INSTRUMENTS	



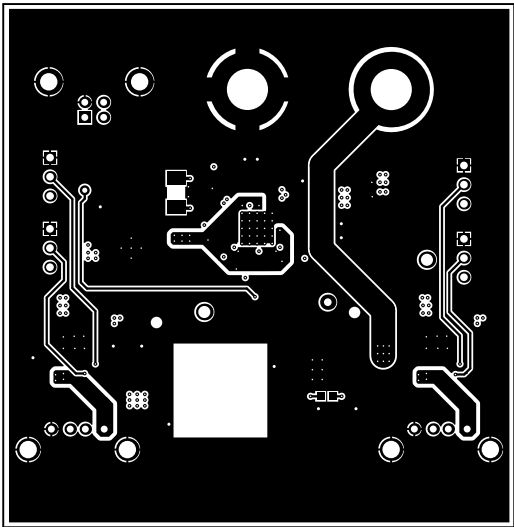
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00887	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: 00887		
PLOT NAME = Top Layer	GENERATED : 7/18/2016 1:36:27 PM	TEXAS INSTRUMENTS	



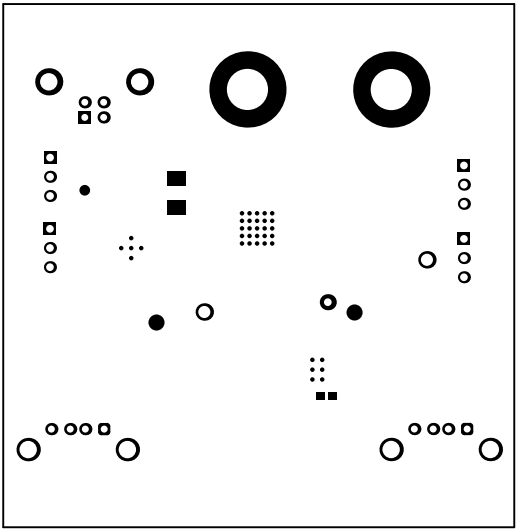
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00887	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: 00887		
PLOT NAME = Signal Layer 1	GENERATED : 7/18/2016 1:36:27 PM	TEXAS INSTRUMENTS	



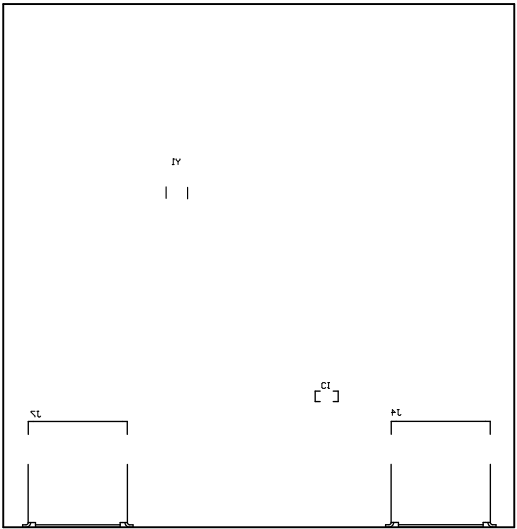
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00887	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: 00887		
PLOT NAME = Signal Layer 2	GENERATED : 7/18/2016 1:36:28 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00887	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: 00887		
PLOT NAME = Bottom Layer	GENERATED : 7/18/2016 1:36:28 PM	TEXAS INSTRUMENTS	

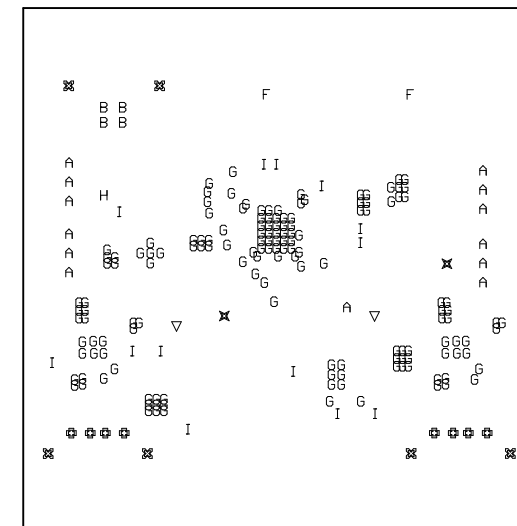


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00887	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 00887		
PLOT NAME = Bottom Solder Mask	GENERATED : 7/18/2016 1:36:29 PM	TEXAS INSTRUMENTS	

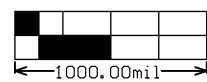
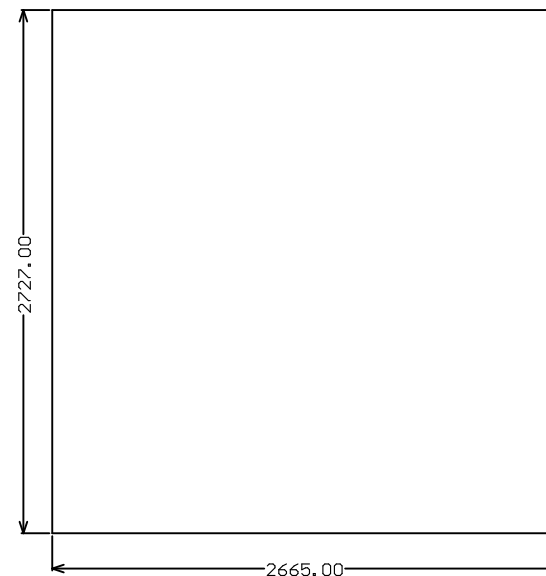


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00887	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 00887		
PLOT NAME = Bottom Overlay	GENERATED : 7/18/2016 1:36:29 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
G	151	7.87mil (0.200mm)	PTH	Round
I	13	16.00mil (0.406mm)	PTH	Round
H	1	26.70mil (0.678mm)	PTH	Round
B	4	36.00mil (0.914mm)	PTH	Round
⊕	8	36.22mil (0.920mm)	PTH	Round
À	13	40.00mil (1.016mm)	PTH	Round
∇	2	60.00mil (1.524mm)	PTH	Round
✕	2	63.00mil (1.600mm)	PTH	Round
✕	6	90.55mil (2.300mm)	PTH	Round
F	2	214.57mil (5.450mm)	PTH	Round
	292 Total			



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00887	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 00887		
PLOT NAME = Drill Drawing	GENERATED : 7/18/2016 1:36:30 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00887	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: 00887		
PLOT NAME = Board Dimensions	GENERATED : 7/18/2016 1:36:31 PM	TEXAS INSTRUMENTS	

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